ABSTRACT OF THE DISCLOSURE

A wafer sheet stretching apparatus is equipped with a stretching mechanism 2 that includes a support ring 7 having a hole 7e at a central part thereof and supporting a wafer sheet 11 retained on a wafer ring 13 by a circular annulus portion 7d formed projectively on an outer-peripheral portion of the hole 7e, a stretching ring 8 that is disposed in such a way as to oppose the support ring 7 and that has an annular portion 8c that is loosely fitted over the circular annulus portion 7d so as to stretch the wafer sheet 12 in cooperation with the circular annulus portion 7d and an approaching/separating mechanism 9 for causing relative movement of the support ring 7 and stretching ring 8 in the direction of their being approached to or separated from each other, and a rotating mechanism 3 for supporting the stretching mechanism 2 so that this mechanism may be freely rotatable about an axis that orthogonally intersects a sheet surface of the wafer sheet 11 supported on the circular annulus portion 7d, whereby the approaching/separating mechanism 9 and the rotating mechanism 3 are connected to single drive means 4 through power-switching means 5.

This Sheet Has Been Replaced

